HIGH-RESOLUTION UNCOOLED THERMAL IMAGING CORE



Crius XP 640 (NEW)



EXTREME PERFORMANCE WITH ULTRA-COMPACT VGA THERMAL IMAGING CORE

KEY FEATURES



ADVANCED SHUTTERLESS IMAGING WITH EMBEDDED CORRECTION



CONTOUR ENHANCEMENT: SHARPER DRI AND SUPERIOR OBJECT CLARITY



COLUMN AND TEMPORAL DENOISING: NETD halved from 40 mK to 20 mK



CONTRAST SHARPNESS CORE FOR AUTOFOCUS MANAGMENT

The Crius XP (Extreme Performance) 640 is a cutting-edge uncooled LWIR thermal core, delivering ultra-sharp 640×480 resolution with a 12 μm pixel pitch and NETD <20 mK for exceptional thermal sensitivity.

Engineered for mission-critical defense applications, it features a next-gen shutterless algorithm for rapid imaging (<0.7s) and enhanced stability across extreme temperatures. Advanced contour enhancement deliver sharper contrast, superior dynamic range, and significantly improved DRI and object recognition.

Its compact SWaP design and flexible interface options ensure seamless integration into high-demand platforms, making it the ideal choice for modern thermal imaging systems.

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KEY PERFORMANCES

Sensor	Micro-bolometer technology
Resolution / Pixel Pitch	640 x 480 pixels / 12 μm
Spectral Range	8 – 14 μm
Max NETD (F/1; 300K; 30 Hz)	< 20 mK with denoising
Operating temperature range	-20°C to +60°C
Power consumption (DF40)	< 1.2 W
Qualification	MIL-STD-810G – Method 514 Vibration: 10Hz - 2kHz 13.95g per axis 10h per axis

FUNCTIONS & INTERFACES

Image processing	BPC (Bad Pixel Correction), NUC (Non- Uniformity Correction), Shutterless NUC
Image optimisation	AGC (Automatic Gain Control)
Output options	CL, SDI, DF40
Additional option	On DF40: Handheld/manual control interface + micro display interface
Dimensions (L x B x H) (DF40)	30 x 30 x 23 mm ³
Weight (DF40)	< 38 gr







